

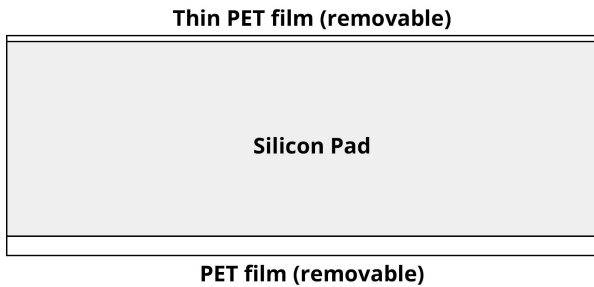
EC360 GREEN

Thermal Pad Series

The EC360® GREEN series presents silicone-based thermal pads for a low price, featuring a balanced thermal conductivity of 2.5 W/mK, suitable for most applications, commonly installed on memory chips and other electrical components. The perfect solution for heat-transfer in adverse surface

conditions when the use of thermal paste is unsuitable. Being based on silicone, they have good elasticity and compression abilities. This means this type of thermal pad will spring back into its original form even after longer periods of compression and perfectly adapt to any tiny surface irregularity.

Cross-Section View



A full silicone pad covered with a PET film on both contact surfaces for increased stability and easy installation. Both are to be removed for installation.

* Custom configurations are available upon request, for worldwide industrial inquiries please contact us at: sales@extremecool360.com

Types and Configurations

Thickness*	Available sizes*
0.5 mm / 0.02 "	50x50 mm, 100x100 mm, 200x200 mm
1.0 mm / 0.04 "	50x50 mm, 100x100 mm, 200x200 mm
1.5 mm / 0.06 "	50x50 mm, 100x100 mm, 200x200 mm
2.0 mm / 0.08 "	50x50 mm, 100x100 mm, 200x200 mm
3.0 mm / 0.12 "	50x50 mm, 100x100 mm, 200x200 mm
4.0 mm / 0.16 "	50x50 mm, 100x100 mm, 200x200 mm
5.0 mm / 0.20 "	50x50 mm, 100x100 mm, 200x200 mm

Technical Properties

Properties	Unit	Value	Test method
Color	-	green	Visual
Thermal Conductivity	W/mK	2.5	ASTM D5470
Specific Gravity	g / cm ³	2.0	ASTM D 792
Hardness	Shore OO	40	ASTM D 2240
Tensile Strength	psi	6.8	ASTM D 412
Elongation	%	12	ASTM D 412
Volume Impedance	Ohm-cm	1.0 x10 ¹¹	ASTM D 257
Breakdown Voltage	kV/mm	6.0	ASTM D 149
Dielectric Constant	1Mhz	5.0	ASTM D 150
Usable Temperatures	°C	-60 - 200	EN 344
Flame Rating	-	VO	UL 94

Installation Recommendation

- Clean surfaces from dirt and other possible residue. If applicable, isopropyl 90% alcohol is recommended to ensure a clean surface.
- Remove one of the protective layers and place the exposed side of the thermal pad facing the surface of the chip. Once positioned gently press on it to make it stick.
- Remove the second protective layer and install the heatsink.